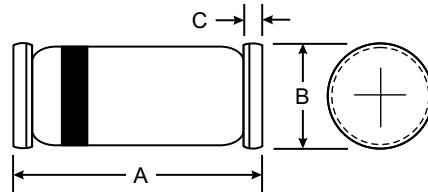


Features

- Fast Switching Speed
- Suitable for General Logic Applications
- High Conductance



Mechanical Data

- Case: MiniMELF, Glass
- Terminals: Solderable per MIL-STD-202, Method 208
- Marking: Cathode Band Only
- Polarity: Cathode Band
- Weight: 0.05 grams (approx.)

MiniMELF		
Dim	Min	Max
A	3.30	3.70
B	1.30	1.60
C	0.28	0.50

All Dimensions in mm

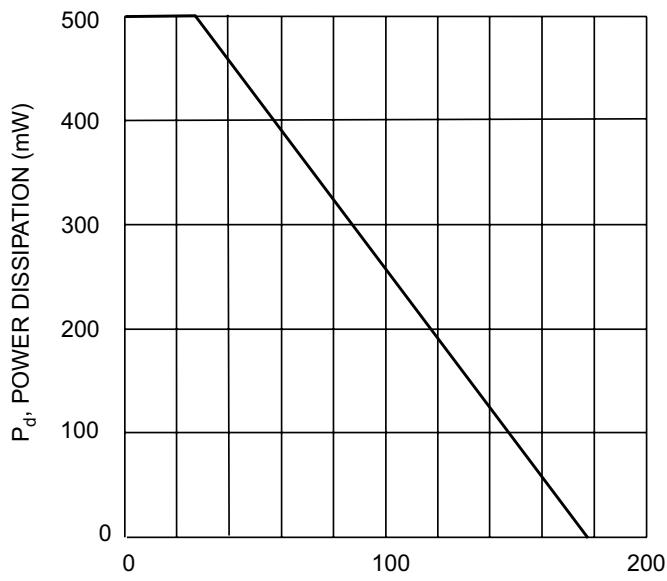
Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	LL4154	Unit
Non-Repetitive Peak Reverse Voltage	V_{RM}	35	V
Peak Repetitive Reverse Voltage	V_{RRM}		
Working Peak Reverse Voltage	V_{RWM}	25	V
DC Blocking Voltage	V_R		
RMS Reverse Voltage	$V_{R(RMS)}$	18	V
Average Rectified Output Current (Note 1)	I_O	150	mA
Non-Repetitive Peak Forward Surge Current @ $t \leq 1.0\text{s}$ @ $t = 1.0\mu\text{s}$	I_{FSM}	0.5 2.0	A
Power Dissipation (Note 1)	P_d	500	mW
Thermal Resistance, Junction to Ambient Air (Note 1)	$R_{\theta JA}$	300	K/W
Operating and Storage Temperature Range	T_j, T_{STG}	-65 to +175	°C

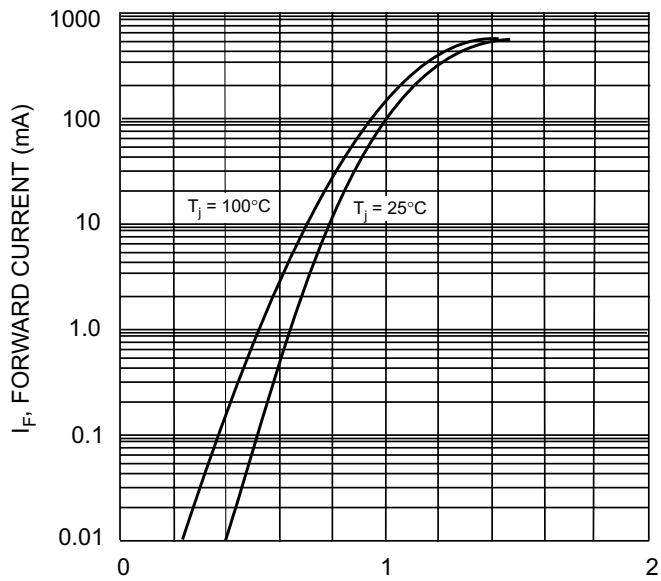
Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
Maximum Forward Voltage Drop	V_{FM}	—	1.0	V	$I_F = 30\text{mA}$
Maximum Peak Reverse Current	I_{RM}	—	100	nA μA	$V_R = 25\text{V}$ $V_R = 25\text{V}, T_j = 150^\circ\text{C}$
Junction Capacitance	C_j	—	4.0	pF	$V_R = 0\text{V}, f = 1.0\text{MHz}$
Reverse Recovery Time	t_{rr}	—	4.0	ns	$I_F = I_R = 10\text{mA},$ $I_{rr} = 0.1 \times I_R, R_L = 100\Omega$

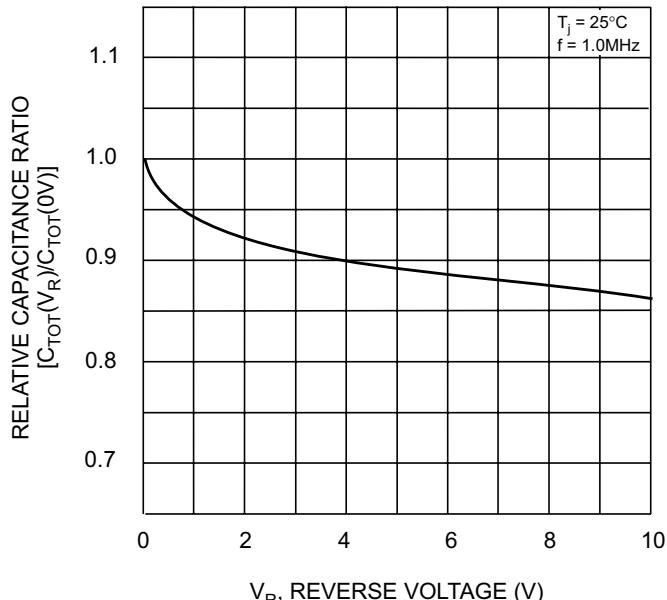
Note: 1. Valid provided that electrodes are kept at ambient temperature.



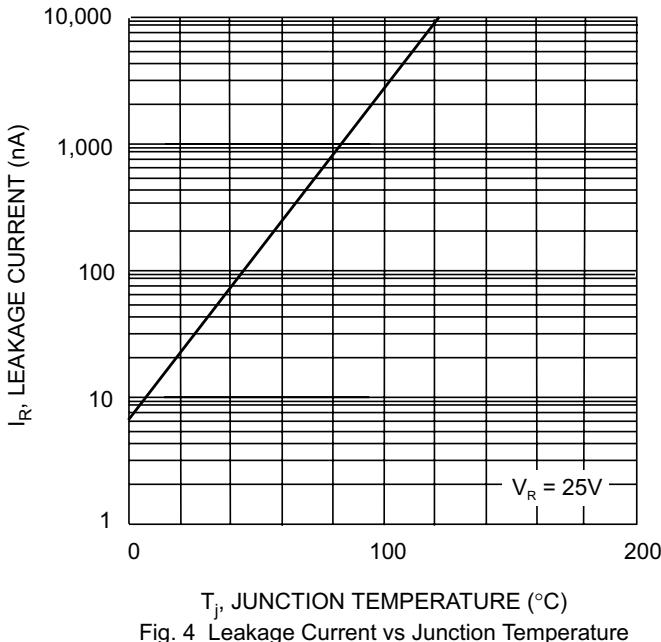
T_A , AMBIENT TEMPERATURE (°C)
Fig. 1 Power Derating Curve



V_F , FORWARD VOLTAGE (V)
Fig. 2 Forward Characteristics



V_R , REVERSE VOLTAGE (V)
Fig. 3 Relative Capacitance Variation



T_j , JUNCTION TEMPERATURE (°C)
Fig. 4 Leakage Current vs Junction Temperature